

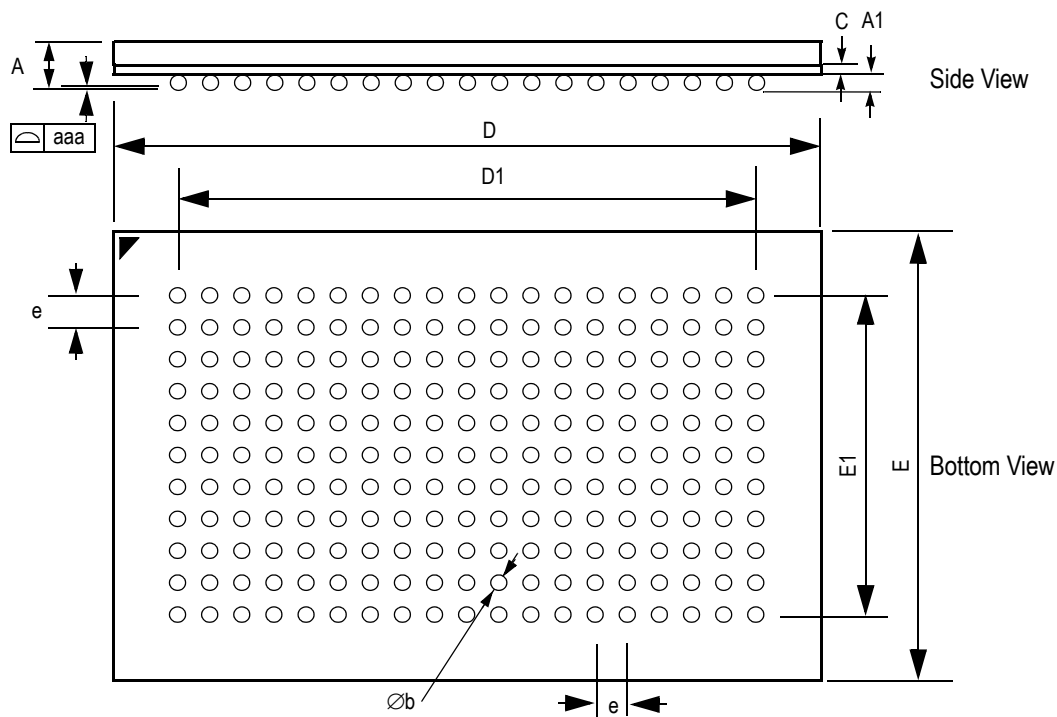
209-Bump BGA (14 mm x 22 mm) DummyDie™ Daisy Chain Package

Description

This mechanical daisy chain test vehicle is designed to represent the 209-Bump BGA package. It is used for second level interconnect assembly test and continuity verification. The DummyDie™ incorporates a 10 mm x 15 mm die, which is not electrically connected.

209 BGA Package Drawing (Package C)

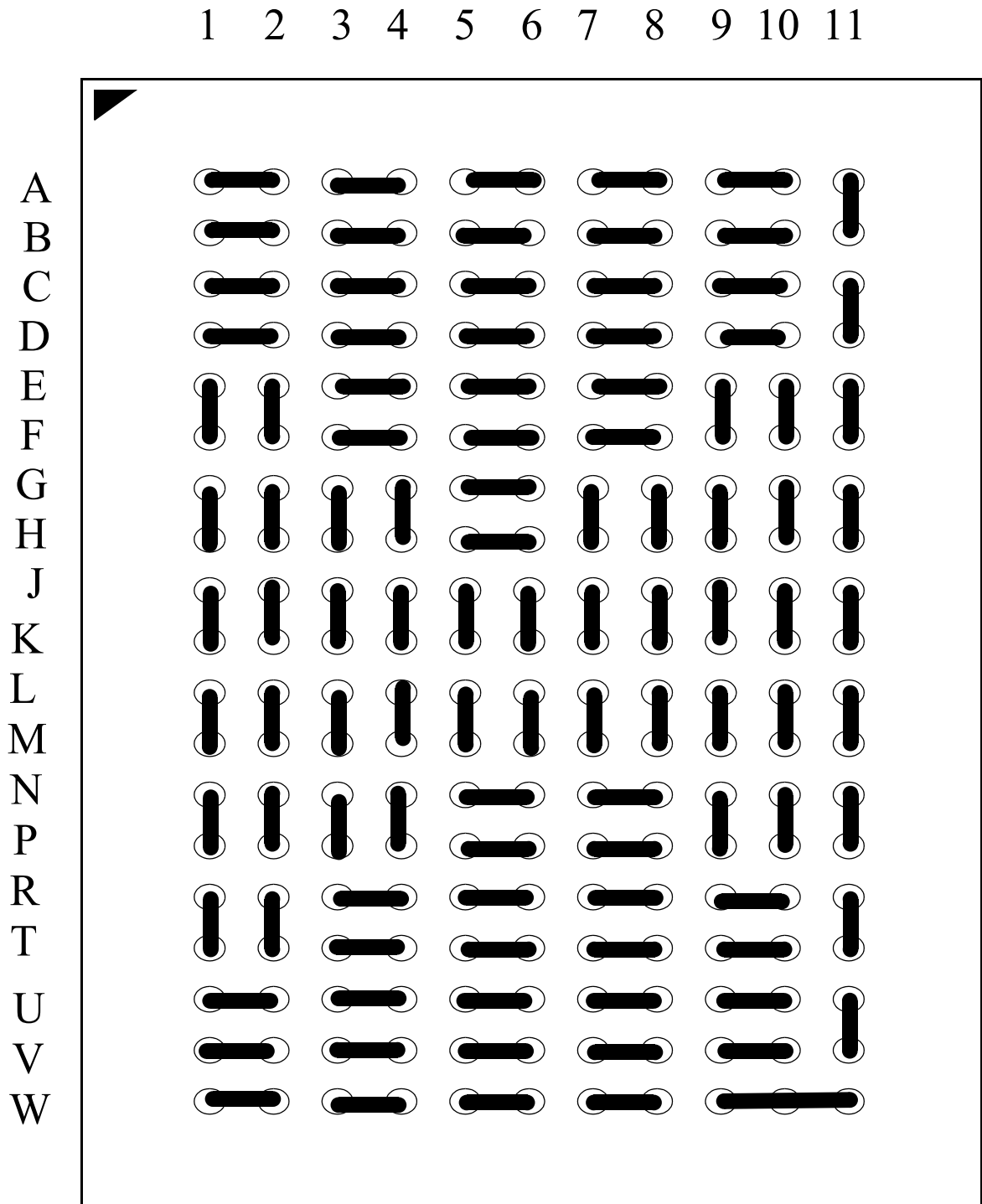
14 mm x 22 mm Body, 1.0 mm Bump Pitch, 11 x 19 Bump Array



Symbol	Min	Typ	Max	Units	Symbol	Min	Typ	Max	Units
A	—	—	1.70	mm	D1	—	18.0 (BSC)	—	mm
A1	0.40	0.50	0.60	mm	E	13.9	14.0	14.1	mm
Øb	0.50	0.60	0.70	mm	E1	—	10.0 (BSC)	—	mm
c	0.31	0.36	0.38	mm	e	—	1.00 (BSC)	—	mm
D	21.9	22.0	22.1	mm	aaa	—	0.15	—	mm

Rev 1.0

209 BGA Interconnection Diagram



Ordering Information

209-Bump BGA (14 mm x 22 mm)
Daisy Chain Package

GSDC209ADC



209-Bump BGA (14 mm x 22 mm)
Daisy Chain Package
RoHS-compliant Option

GSDC209ADGC

